

L Number	Hits	Search Text	DB	Time stamp
-	2	4775235.pn.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/26 18:59
-	3	("4171917" "4553844" "4627734").PN.	USPAT	2003/02/24 11:46
-	21	4775235.URPN.	USPAT	2003/02/24 11:49
-	3	("4171917" "4553844" "4627734").PN.	USPAT	2003/02/24 12:04
-	42	4627734.URPN.	USPAT	2003/02/24 12:04
-	9	("3813140" "3826578" "3986774" "4170398" "4171917" "4218142" "4246612" "4329012" "4373804").PN.	USPAT	2003/02/24 12:08
-	3	("3667846" "3885875" "4171917").PN.	USPAT	2003/02/24 12:09
-	12	4553844.URPN.	USPAT	2003/02/24 12:09
-	12	4553844.URPN.	USPAT	2003/02/24 12:11
-	5	("3866038" "3986774" "4171917" "4373804" "4627734").PN.	USPAT	2003/02/24 12:23
-	10	5111056.URPN.	USPAT	2003/02/24 12:24
-	426	250/559.44.cccls.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/24 18:25
-	53	250/559.44.cccls. and substrate\$1	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/25 10:42
-	10	("4142107" "4303341" "4408884" "4815854" "4953982" "5076692" "5164790" "5361137" "5422723" "5777729").PN.	USPAT	2003/02/24 17:39
-	3	("5465152" "5574801" "5621530").PN.	USPAT	2003/02/24 17:54
-	1	09/888205	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/24 18:00
-	0	09/954404	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/24 18:00
-	11	5020006.URPN.	USPAT	2003/02/24 18:16
-	373	250/559.44.cccls. not (250/559.44.cccls. and substrate\$1)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/24 18:28
-	10	250/559.44.cccls. and penetrat\$3	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/24 18:28
-	53	250/559.44.cccls. and substrate\$1	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/25 10:42
-	25	250/559.44.cccls. and semiconductor\$1 not (250/559.44.cccls. and substrate\$1)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/25 12:05
-	4656	semiconductor with wafer and detect\$3 with (pattern or mark)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/25 14:37
-	1	5942763.URPN.	USPAT	2003/02/25 11:29

-	1755	1 "5465145".PN. semiconductor with wafer and detect\$3 with (pattern or mark) and wavelength\$1	USPAT USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/02/25 11:29 2003/02/25 14:44
-		7 250/559.44.ccls. and wafer not ((250/559.44.ccls. and substrate\$1) or (250/559.44.ccls. and semiconductor\$1 not (250/559.44.ccls. and substrate\$1)))		2003/02/25 12:05
-		5 semiconductor with wafer and detect\$3 with (pattern or mark) and wavelength\$1 with oxide adj layer\$1		2003/02/25 12:51
-	190	250/559.01.ccls.		2003/02/25 13:50
-		2 5852497.pn.		2003/02/25 13:15
-	4	5852497.URPN.	USPAT	2003/02/25 13:14
-	29	pramanik-dipankar.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/02/25 13:15
-	7	6071177.URPN.	IBM TDB	
-	1	6313542.URPN.	USPAT	2003/02/25 13:24
-	70	250/559.05.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/02/25 13:26
-	4064	reflectometer	IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/02/25 14:44
-	30	(US-4775235-\$ or US-4627734-\$ or US-4553844-\$ or US-5111056-\$ or US-4329012-\$ or US-6423977-\$ or US-6091075-\$ or US-5811792-\$ or US-5721435-\$ or US-4348592-\$ or US-5777729-\$ or US-5361137-\$ or US-5076692-\$ or US-4953982-\$ or US-4142107-\$ or US-6240218-\$ or US-5543921-\$ or US-5942763-\$ or US-5896192-\$ or US-4926049-\$ or US-5465145-\$ or US-6071177-\$ or US-5852497-\$ or US-6315917-\$ or US-6501189-\$).did. or (US-20030001076-\$ or US-20020186374-\$).did. or (JP-04282441-\$ or JP-04016752-\$).did. or (US-6313542-\$).did.	IBM TDB USPAT; US-PGPUB; JPO; DERWENT	2003/02/25 14:36

-	2	((US-4775235-\$ or US-4627734-\$ or US-4553844-\$ or US-5111056-\$ or US-4329012-\$ or US-6423977-\$ or US-6091075-\$ or US-5811792-\$ or US-5721435-\$ or US-4348592-\$ or US-5777729-\$ or US-5361137-\$ or US-5076692-\$ or US-4953982-\$ or US-4142107-\$ or US-6240218-\$ or US-5543921-\$ or US-5942763-\$ or US-5896192-\$ or US-4926049-\$ or US-5465145-\$ or US-6071177-\$ or US-5852497-\$ or US-6315917-\$ or US-6501189-\$).did. or (US-20030001076-\$ or US-20020186374-\$).did. or (JP-04282441-\$ or JP-04016752-\$).did. or (US-6313542-\$).did.) and reflectometer	USPAT; US-PGPUB; JPO; DERWENT	2003/02/25 14:37
-	40	semiconductor with wafer and detect\$3 with (pattern or mark) and reflectometer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/25 14:38
-	40	semiconductor with wafer and detect\$3 with (pattern or mark) and wavelength\$1 and reflectometer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/25 17:58
-	107	250/559.06.cccls.	USPAT;	2003/02/25 14:45
-	111	250/559.06.cccls.	USPAT; US-PGPUB	2003/02/25 14:51
-	96	250/559.07.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/25 15:12
-	214	250/559.39.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/25 16:28
-	526	257/797.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/25 15:13
-	20	semiconductor with wafer and align\$4 with mark and wavelength\$1 and reflectometer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/25 16:16
-	584	250/559.4.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/25 16:51
-	196	250/559.4.cccls. and (semiconductor or substrate or mark)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/25 16:29
-	103	250/559.43.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/25 16:51

-	38	(US-5889593-\$ or US-6258611-\$ or US-6259525-\$ or US-6242816-\$ or US-5925937-\$ or US-4627734-\$ or US-4553844-\$ or US-4775235-\$ or US-5111056-\$ or US-5811792-\$ or US-6423977-\$ or US-6091075-\$ or US-5942763-\$ or US-5896192-\$ or US-5721435-\$ or US-4329012-\$ or US-4926049-\$ or US-4348592-\$ or US-5361137-\$ or US-4953982-\$ or US-5777729-\$ or US-4142107-\$ or US-5076692-\$ or US-6240218-\$ or US-5543921-\$ or US-5465145-\$).did. or (US-6071177-\$ or US-5852497-\$ or US-6313542-\$ or US-6315917-\$ or US-6501189-\$ or US-4896034-\$).did. or (US-20030001076-\$ or US-20020186374-\$ or US-20030039388-\$).did. or (JP-04282441-\$ or JP-04016752-\$).did. or (US-6313542-\$).did.	USPAT; US-PPGPUB; JPO; DERWENT	2003/02/27 17:58
-	9	((US-5889593-\$ or US-6258611-\$ or US-6259525-\$ or US-6242816-\$ or US-5925937-\$ or US-4627734-\$ or US-4553844-\$ or US-4775235-\$ or US-5111056-\$ or US-5811792-\$ or US-6423977-\$ or US-6091075-\$ or US-5942763-\$ or US-5896192-\$ or US-5721435-\$ or US-4329012-\$ or US-4926049-\$ or US-4348592-\$ or US-5361137-\$ or US-4953982-\$ or US-5777729-\$ or US-4142107-\$ or US-5076692-\$ or US-6240218-\$ or US-5543921-\$ or US-5465145-\$).did. or (US-6071177-\$ or US-5852497-\$ or US-6313542-\$ or US-6315917-\$ or US-6501189-\$ or US-4896034-\$).did. or (US-20030001076-\$ or US-20020186374-\$ or US-20030039388-\$).did. or (JP-04282441-\$ or JP-04016752-\$).did. or (US-6313542-\$).did.) and processor	USPAT; US-PPGPUB; JPO; DERWENT	2003/02/27 18:44
-	13	((US-5889593-\$ or US-6258611-\$ or US-6259525-\$ or US-6242816-\$ or US-5925937-\$ or US-4627734-\$ or US-4553844-\$ or US-4775235-\$ or US-5111056-\$ or US-5811792-\$ or US-6423977-\$ or US-6091075-\$ or US-5942763-\$ or US-5896192-\$ or US-5721435-\$ or US-4329012-\$ or US-4926049-\$ or US-4348592-\$ or US-5361137-\$ or US-4953982-\$ or US-5777729-\$ or US-4142107-\$ or US-5076692-\$ or US-6240218-\$ or US-5543921-\$ or US-5465145-\$).did. or (US-6071177-\$ or US-5852497-\$ or US-6313542-\$ or US-6315917-\$ or US-6501189-\$ or US-4896034-\$).did. or (US-20030001076-\$ or US-20020186374-\$ or US-20030039388-\$).did. or (JP-04282441-\$ or JP-04016752-\$).did. or (US-6313542-\$).did.) and wavelengths	USPAT; US-PPGPUB; JPO; DERWENT	2003/02/27 19:58
-	0	little-joseph.in.	USPAT; US-PPGPUB; JPO; DERWENT	2003/02/27 19:58
-	0	little-joseph.in.	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/02/27 19:58

-	16	little-j.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/27 19:58
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